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(54) POLYIMIDE FILM AND PREPARATION THEREOF

(57)Abstract:

PROBLEM TO BE SOLVED: To provide a polyimide film with improved durability of adhesion strength against a high temperature, high humidity environment without adversely affecting the external appearance of the polyimide film to be used as a base film of flexible printed circuit boards.

SOLUTION: The surface of a partially cured or partially dried polyamic acid film having an imidation ratio of not less than 50% is coated with a solution of an organic titanium compound or a partially cured or partially dried polyamic acid film having an imidation ratio of not less than 50% is impregnated with a solution of a titanium compound and then, the polyamic acid film is converted into a polyimide film which is then dried. As a result, in the surface of this polyimide film are introduced titanium atoms at a concentration of the number of atoms of 0.01%–10% measured by X-ray photoelectron spectroscopy and thus, the polyimide film is improved in the durability of adhesion strength against a high temperature, high humidity environment without spoiling the external appearance of the film.

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